## SN65LVDM1676供应商

## SN65LVDM1676, SN65LVDM1677 HIGH-SPEED DIFFERENTIAL LINE TRANSCEIVERS

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<ul> <li>Sixteen Low-Voltage Differential Transceivers Designed for Signaling Rates<sup>†</sup> Up to 630 Mbps</li> </ul>	SN65LVDM1677I		ed as LVDM1676) d as LVDM1677)
<ul> <li>Simplex (Point-to-Point) and Half-Duplex (Multipoint) Interface</li> </ul>	GND [ V <sub>CC</sub> [		] A1Y ] A1Z
<ul> <li>Typical Differential Output Voltage of 340 mV Into a 50-Ω Load</li> </ul>		3 62	] A2Y ] A2Z
<ul> <li>Integrated 110-Ω Line Termination on 'LVDM1677 Product</li> </ul>	ATX/RX [ A1A [	6 59	] A3Y ] A3Z
<ul> <li>Propagation Delay Time:</li> <li>Driver: 2.5 ns Typ</li> </ul>	A2A [ A3A [ A4A [	8 57	] A4Y ] A4Z ] B1Y
<ul> <li>Receiver: 3 ns Typ</li> <li>Recommended Maximum Transfer Rate:         <ul> <li>Driver: 650 M-Transfers/s</li> </ul> </li> </ul>	BTX/RX [ B1A [	10 55 11 54	] B1Z ] B2Y
<ul> <li>Receiver: 350 M-Transfers/s</li> <li>Driver is High Impedance When Disabled or</li> </ul>	B2A [ B3A [	13 52	] B2Z ] B3Y
With V <sub>CC</sub> < 1.5 V for Power Up/Down Glitch-Free Performance and Hot-Plugging Events	B4A [ GND [ V <sub>CC</sub> [	15 50	] B3Z ] B4Y ] B4Z
<ul> <li>Bus-Terminal ESD Protection Exceeds 12 kV</li> </ul>	V <sub>CC</sub> [ GND [ C1A [	18 47	] C1Y ] C1Z ] C2Y
<ul> <li>Low-Voltage TTL (LVTTL) Logic Input Levels Are 5-V Tolerant</li> </ul>	C2A [ C3A [	20 45 21 44	] C2Z ] C3Y
<ul> <li>Packaged in Thin Shrink Small-Outline Package With 20 mil Terminal Pitch</li> </ul>	CTX/RX	23 42	] C3Z ] C4Y
description	DTA [ D2A [ D3A [	25 40	] C4Z ] D1Y ] D1Z
The SN65LVDM1676 and SN65LVDM1677 (integrated termination) are sixteen differential line drivers and receivers configured as trans- ceivers that use low-voltage differential signaling (LVDS) to achieve signaling rates in excess of 600 Mbps. These products are similar to TIA/EIA-644 standard compliant devices	D4A [ DTX/RX [	<ol> <li>27 38</li> <li>28 37</li> <li>29 36</li> <li>30 35</li> <li>31 34</li> </ol>	] D12 ] D2Y ] D2Z ] D3Y ] D3Z ] D4Y ] D4Z

current of the drivers are doubled. This modification provides a minimum differential output voltage magnitude of 247 mV into a 50- $\Omega$  load and allows double-terminated lines and half-duplex operation. The receivers detect a voltage difference of 100 mV with up to 1 V of ground potential difference between a transmitter and receiver.



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<sup>+</sup> Signaling rate, 1/t, where t is the minimum unit interval and is expressed in the units bits/s (bits per second)

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

(SN65LVDS) counterparts except that the output



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#### description (continued)

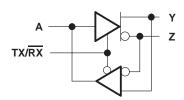
The intended application of this device and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately 100  $\Omega$ . The transmission media may be printed-circuit board traces, backplanes, or cables. The large number of transceivers integrated into the same substrate along with the low pulse skew of balanced signaling, allows extremely precise timing alignment of clock and data for synchronous parallel data transfers. (Note: The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other system characteristics.)

The SN65LVDM1676 and SN65LVDM1677 are characterized for operation from -40°C to 85°C.

FUNCTION TABLE					
_	-	0	OUTPUT	S	
TX/RX	Α	Y	Z	Α	
L	NA	Z	Z	Н	
L	NA	Z	Z	?	
L	NA	Z	Z	L	
L	NA	Z	Z	Н	
Н	L	L	Н	Z	
Н	Н	Н	L	Z	
	TX/RX L L L L H	TX/RXALNALNALNAHL	TX/RXAYLNAZLNAZLNAZLNAZHLL	OUTPUTTX/RXAYZLNAZZLNAZZLNAZZLNAZZHLH	

FUNCTION TABLE

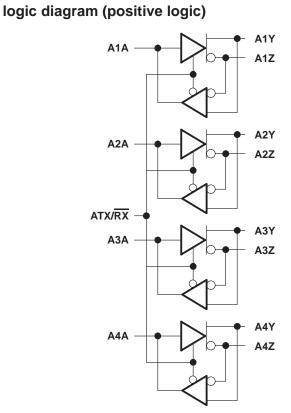
H = high level, L= low level, Z= high impedance, ? = indeterminate

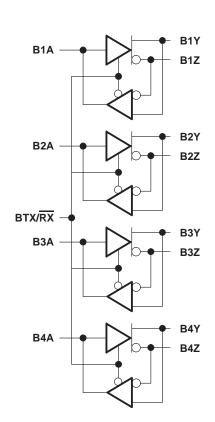


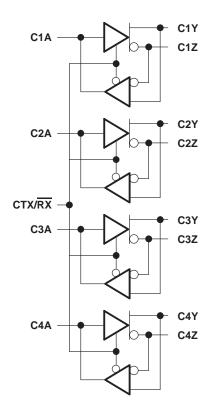
#### LVD Transceiver

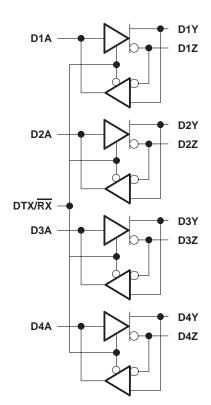


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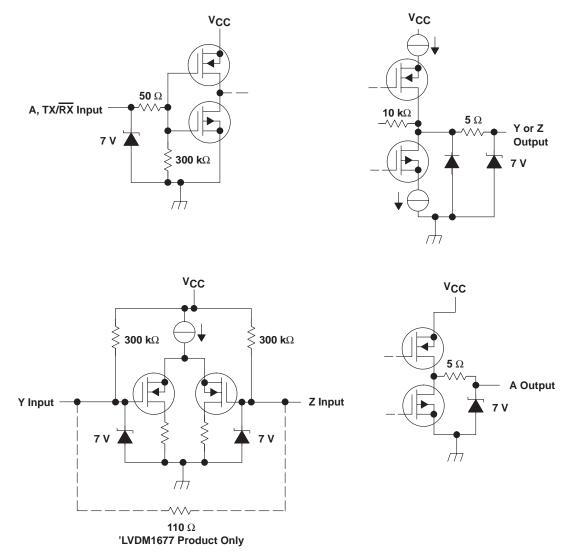






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## equivalent input and output schematic diagrams





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#### absolute maximum ratings over operating free-air temperature (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> (see Note 1) Input voltage range: A, TX/RX Y or Z	–0.5 V to 6 V
Differential input voltage magnitude, V <sub>ID</sub> , (SN65LVDM1677 only)	
Receiver output current, $I_{\Omega}$	
Electrostatic discharge: Y, Z, and GND (see Note 2)	Class 3, A:8 kV, B:600 V
Continuous power dissipation	Class 3, A:7 kV, B:500 V
Storage temperature range	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

2. Tested in accordance with MIL-STD-883C Method 3015.7.

3. This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no airflow.

#### DISSIPATION RATING TABLE

PACKAGE	T <sub>A</sub> ≤ 25°C	OPERATING FACTOR <sup>‡</sup>	T <sub>A</sub> = 85°C
	POWER RATING	ABOVE T <sub>A</sub> = 25°C	POWER RATING
DGG	2094 mW	16.7 mW/°C	1089 mW

<sup>‡</sup> All typical values are at 25°C and with a 3.3-V supply.

#### recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	3	3.3	3.6	V
High-level input voltage, VIH	2			V
Low-level input voltage, VIL			0.8	V
Magnitude of differential input voltage, VID	0.1		0.6	V
Common-mode input voltage, V <sub>IC</sub>	$\frac{ V_{ID} }{2}$		$2.4 - \frac{ V_{ID} }{2}$	V
			VCC-0.8	V
Receiver low-level output current, IOL			8	mA
Receiver high-level output current, IOH	-8			mA
Operating free-air temperature, T <sub>A</sub>	-40		85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

device

	PARAMETER	TEST CONDITIONS	MIN	түр‡	MAX	UNIT
	- Cumply summert	Driver enabled, receiver disabled, RL 50 $\Omega$		140	175	
ICO	C Supply current	Driver disabled, receiver enabled, no load		45	60	mA

<sup>‡</sup>All typical values are at 25°C and with a 3.3-V supply.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

#### driver

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>OD</sub>	Differential output voltage magnitude		247	340	454	
$\Delta  V_{OD} $	Change in differential output voltage magnitude between logic states	$R_L$ = 50 Ω, See Figure 1 and Figure 2	-50		50	mV
VOC(SS)	Steady-state common-mode output voltage		1.125		1.375	V
ΔVOC(SS)	Change in steady-state common-mode output voltage between logic states	See Figure 3	-50		50	mV
VOC(PP)	Peak-to-peak common-mode output voltage			50	150	mV
IIН	High-level input current	$V_{IH} = 2 V$		3	20	μΑ
۱ <sub>IL</sub>	Low-level input current	$V_{IL} = 0.8 V$		2	10	μA
		VOX or $AOZ = 0$ A			10	mA
los	Short-circuit output current	$V_{OD} = 0 V$			10	mA
lO(OFF)	Power-off output current	$V_{CC} = 1.5 V$ , $V_{O} = 2.4 V$			±10	μΑ
C <sub>IN</sub>	Input capacitance	V <sub>I</sub> = 0.4 sin (4E6pt) + 0.5 V		5		pF

#### receiver

	PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V <sub>IT+</sub>	Positive-going differential input voltage three	shold				100	
VIT-	Negative-going differential input voltage three	eshold	See Figure 6 and Table 1	-100			mV
VOH	High-level output voltage		I <sub>OH</sub> = -8 mA	2.4			V
V <sub>OL</sub>	Low-level output voltage		I <sub>OL</sub> = 8 mA			0.4	V
			$V_{I} = 0 V$		-24	-40	
1	Input current (Y or Z inputs)		V <sub>I</sub> = 2.4 V	-1.2	-8		μA
		'LVDM1676	$V_{IY} = 0 V$ and $V_{IZ} = 100 mV$ , $V_{IY} = 2.4 V$ and $V_{IZ} = 2.3 V$		5	10	μA
ID	Differential input current $ I_{IY} - I_{IZ} $ (inputs)	'LVDM1677		1.5		2.2	mA
II(OFF)	Power-off input current (Y or Z inputs)		$V_{CC} = 0 V$ , $V_{I} = 2.4 V$			±25	μA

 $^\dagger$  All typical values are at 25°C and with a 3.3-V supply.



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# switching characteristics over recommended operating free-air temperature range (unless otherwise noted)

#### driver

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output		1.3	2.5	3.6	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output		1.3	2.5	3.6	ns
t <sub>r</sub>	Differential output signal rise time	R <sub>L</sub> = 50 Ω,		0.5	1.2	ns
t <sub>f</sub>	Differential output signal fall time	C <sub>L</sub> = 10 pF,		0.5	1.2	ns
<sup>t</sup> sk(p)	Pulse skew ( t <sub>PHL</sub> – t <sub>PLH</sub>  )	See Figure 4		0.1	0.6	ns
<sup>t</sup> sk(o)	Channel-to-channel output skew <sup>†</sup>			0.1	0.4	ns
<sup>t</sup> sk(pp)	Part-to-part skew <sup>‡</sup>				1	ns
<sup>t</sup> PZH	Propagation delay time, high-impedance-to-high-level output			11	20	ns
<sup>t</sup> PZL	Propagation delay time, high-impedance-to-low-level output	See Figure F		10	20	ns
<sup>t</sup> PHZ	Propagation delay time, high-level-to-high-impedance output	See Figure 5		3	10	ns
<sup>t</sup> PLZ	Propagation delay time, low-level-to-high-impedance output			3	10	ns

t t<sub>sk(0)</sub> is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

<sup>‡</sup> t<sub>sk(PP)</sub> is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

#### receiver

	PARAMETER	TEST CONDITIONS	MIN	TYP§	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output		1.5	3	4.5	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output		1.5	3	4.5	ns
t <sub>r</sub>	Output signal rise time			0.6	1.6	ns
t <sub>f</sub>	Output signal fall time	CL = 10 pF, See Figure 7		0.6	1.6	ns
<sup>t</sup> sk(p)	Pulse skew ( t <sub>PHL</sub> – t <sub>PLH</sub>  )			0.2	0.8	ns
<sup>t</sup> sk(o)	Channel-to-channel output skew <sup>†</sup>			0.7	1.2	ns
<sup>t</sup> sk(pp)	Part-to-part skew <sup>‡</sup>				1	ns
<sup>t</sup> PZH	Propagation delay time, high-impedance-to-high-level output	See Figure 8		9	15	ns
t <sub>PZL</sub>	Propagation delay time, high-impedance-to-low-level output	See Figure 8		8	15	ns
<sup>t</sup> PHZ	Propagation delay time, high-level-to-high-impedance output	Coo Figuro 9		12	20	ns
<sup>t</sup> PLZ	Propagation delay time, low-level-to-high-impedance output	See Figure 8		11	20	ns

<sup>†</sup> t<sub>sk(0)</sub> is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

<sup>‡</sup> t<sub>sk(pp)</sub> is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

§ All typical values are at 25°C and with a 3.3-V supply.



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## PARAMETER MEASUREMENT INFORMATION

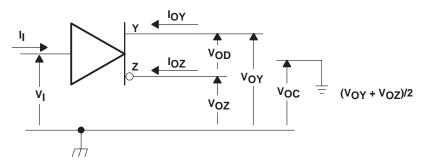


Figure 1. Driver Voltage and Current Definitions

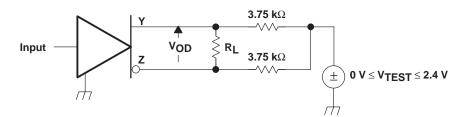
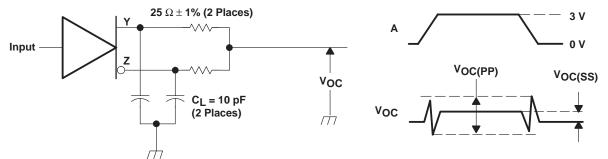


Figure 2. Driver V<sub>OD</sub> Test Circuit



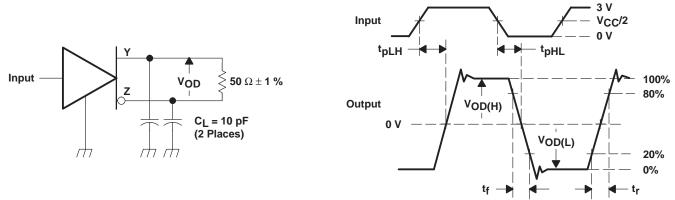
NOTE: All input pulses are supplied by a generator having the following characteristics: t<sub>f</sub> or t<sub>f</sub> ≤ 1 ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C<sub>L</sub> includes instrumentation and fixture capacitance within 0,06 m of the D.U.T. The measurement of V<sub>OC(PP)</sub> is made on test equipment with a –3 dB bandwidth of at least 300 MHz.

Figure 3. Test Circuit and Definitions for the Driver Common-Mode Output Voltage



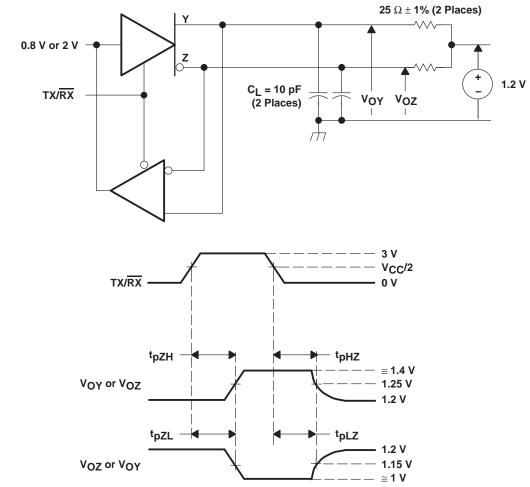
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## PARAMETER MEASUREMENT INFORMATION



NOTE: All input pulses are supplied by a generator having the following characteristics:  $t_f$  or  $t_f \le 1$  ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 10 ± 0.2 ns. C<sub>L</sub> includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

#### Figure 4. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal



NOTE: All input pulses are supplied by a generator having the following characteristics:  $t_f$  or  $t_f \le 1$  ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C<sub>L</sub> includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

#### Figure 5. Enable and Disable Time Circuit and Definitions



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## PARAMETER MEASUREMENT INFORMATION

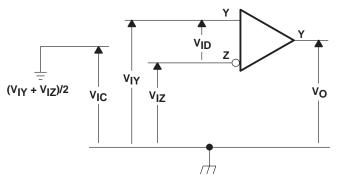
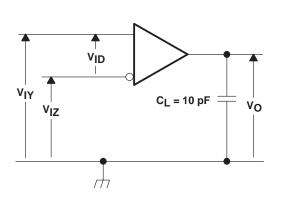
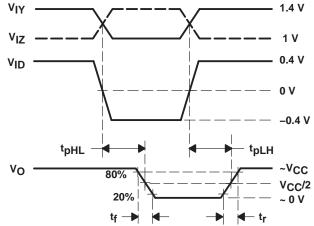


Figure 6. Voltage Definitions

APPLIED	/OLTAGES	RESULTING DIFFERENTIAL INPUT VOLTAGE	RESULTING COMMON- MODE INPUT VOLTAGE
VIY	VIZ	V <sub>ID</sub>	VIC
1.25 V	1.15 V	100 mV	1.2 V
1.15 V	1.25 V	–100 mV	1.2 V
2.4 V	2.3 V	100 mV	2.35 V
2.3 V	2.4 V	–100 mV	2.35 V
0.1 V	0 V	100 mV	0.05 V
0 V	0.1 V	–100 mV	0.05 V
1.5 V	0.9 V	600 mV	1.2 V
0.9 V	1.5 V	–600 mV	1.2 V
2.4 V	1.8 V	600 mV	2.1 V
1.8 V	2.4 V	–600 mV	2.1 V
0.6 V	0 V	600 mV	0.3 V
0 V	0.6 V	–600 mV	0.3 V





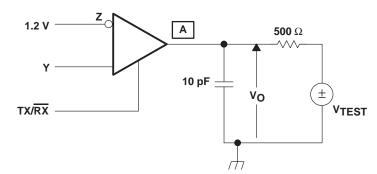
NOTE: All input pulses are supplied by a generator having the following characteristics:  $t_f$  or  $t_f \le 1$  ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 10 ± 0.2 ns. CL includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.



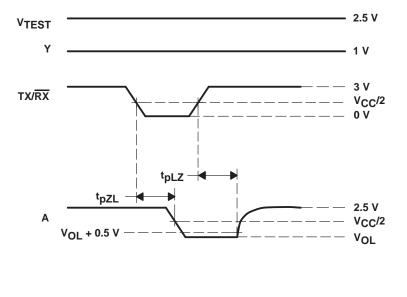


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### PARAMETER MEASUREMENT INFORMATION



NOTE: All input pulses are supplied by a generator having the following characteristics:  $t_{f}$  or  $t_{f} \leq 1$  ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500  $\pm$  10 ns. CL includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.



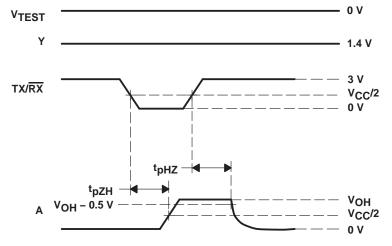
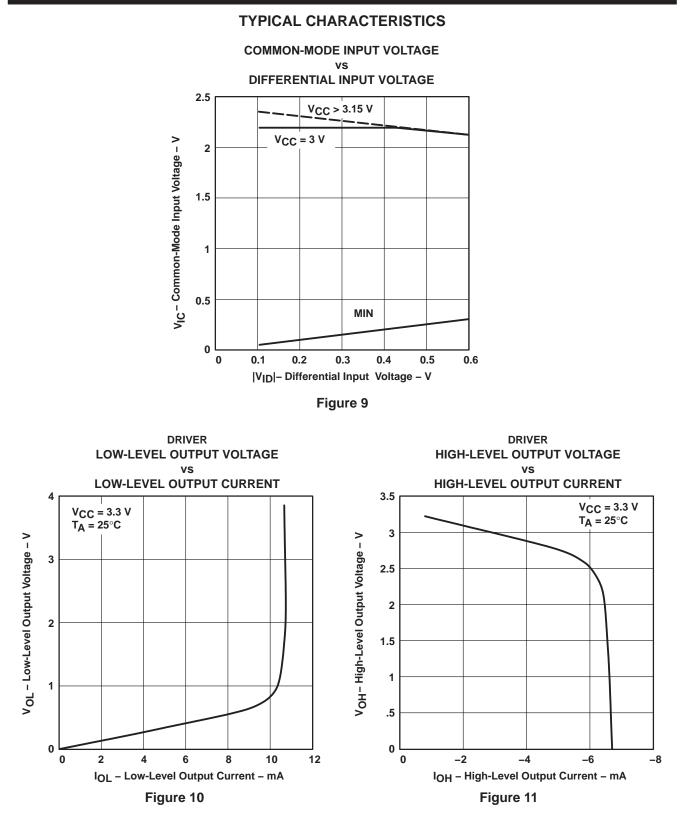


Figure 8. Enable/Disable Time Test Circuit and Waveforms

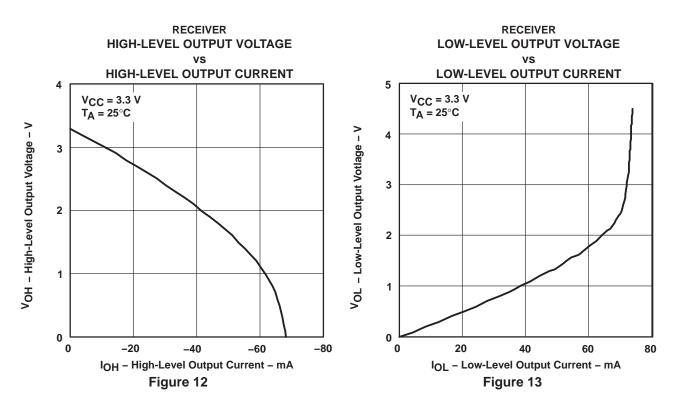


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### **TYPICAL CHARACTERISTICS**



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## TYPICAL CHARACTERISTICS

## driver eye pattern

#### test conditions

- V<sub>CC</sub> = 3.3 V
- $T_A = 25^{\circ}C$  (ambient temperature)
- All 16 channels switching simultaneously with NRZ data. Scope is triggered at the same frequency with pulse. Input signal level = 0 to 3 V single ended.
- Resistive loading with no added capacitance

#### equipment

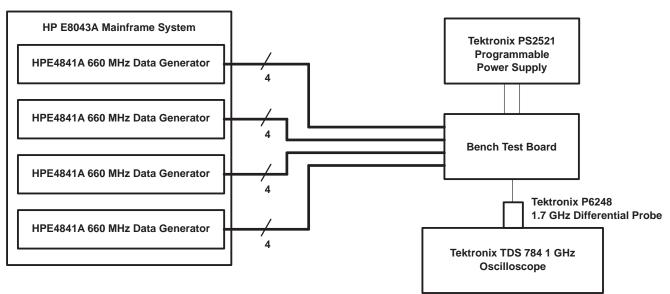
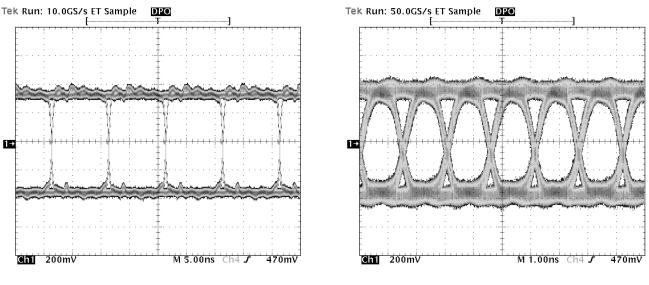


Figure 14. Driver Test Equipment Setup



100 Mbps

650 Mbps





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## **TYPICAL CHARACTERISTICS**

#### receiver eye pattern

#### test conditions

- V<sub>CC</sub> = 3.3 V
- $T_A = 25^{\circ}C$  (ambient temperature)
- All 16 channels switching simultaneously with NRZ data. Scope is pulse-triggered simultaneously with NRZ data. Input signal level is 1 V to 1.4 V differential.
- 50-Ω resistive loading with no added capacitance

#### equipment

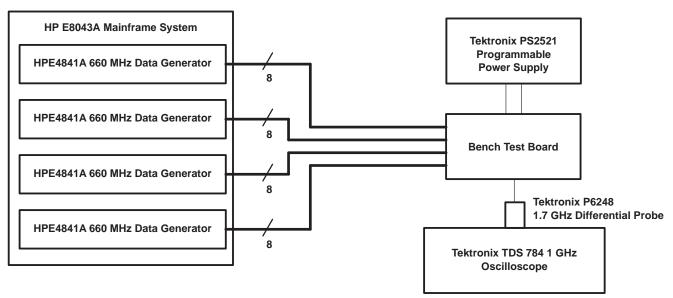
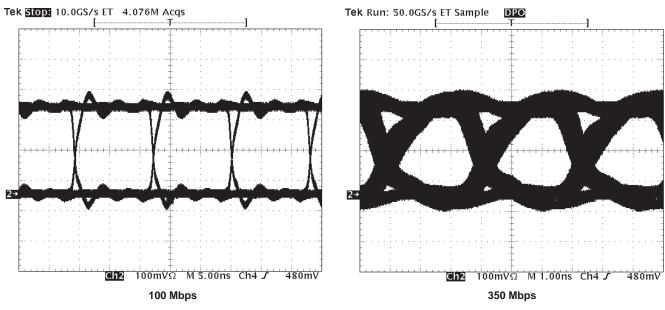


Figure 16. Receiver Test Equipment Setup







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## **APPLICATION INFORMATION**

#### fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –50 mV and 50 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different, however, in how it handles the open-input circuit situation.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near  $V_{CC}$  through 300-k $\Omega$  resistors as shown in Figure 18. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level, regardless of the differential input voltage.

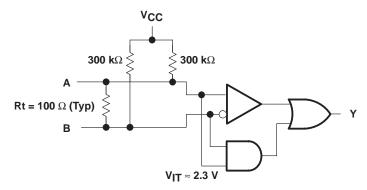


Figure 18. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver will be valid with less than a 50-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.

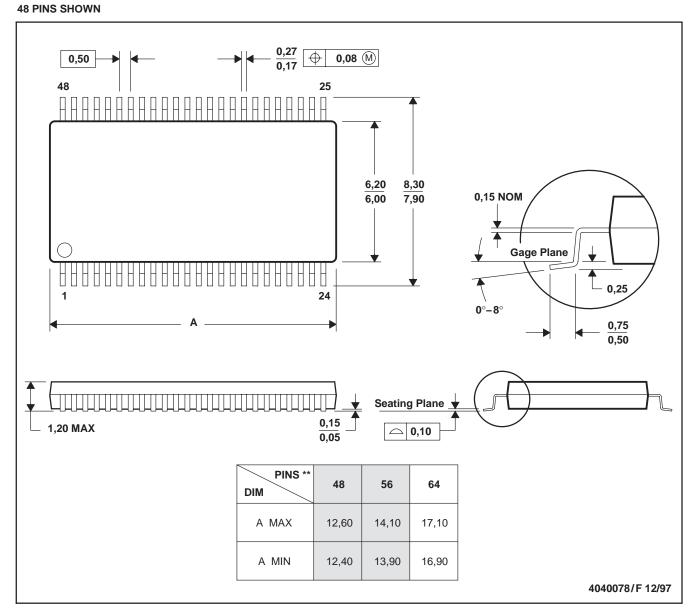


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## **MECHANICAL DATA**

#### PLASTIC SMALL-OUTLINE PACKAGE

DGG (R-PDSO-G\*\*)



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



TEXAS NSTRUMENTS

### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN65LVDM1676DGG	ACTIVE	TSSOP	DGG	64	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDM1676DGGG4	ACTIVE	TSSOP	DGG	64	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDM1676DGGR	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDM1676DGGRG4	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDM1677DGG	ACTIVE	TSSOP	DGG	64	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDM1677DGGG4	ACTIVE	TSSOP	DGG	64	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDM1677DGGR	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDM1677DGGRG4	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# **MECHANICAL DATA**

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

#### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

**48 PINS SHOWN** 



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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